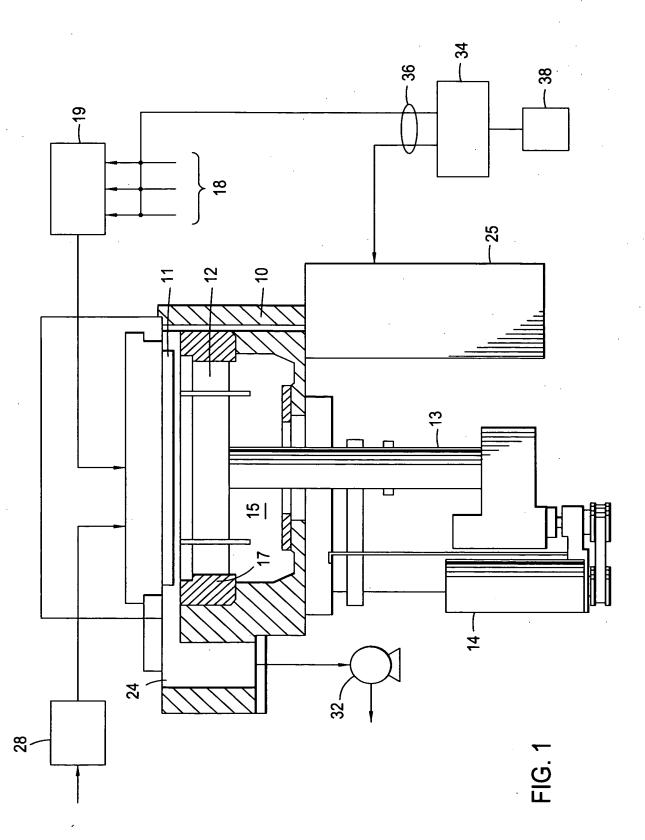
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TITLE: ULTRA LOW DIELECTRIC MATERIALS BASED ON HYBRID
SYSTEM OF LINEAR SILICON PRECURSOR
KANG SUB YIM, ET AL.

INVENTOR:

EXPRESS MAIL No.: EV335471710US

PAGE 1 OF 6

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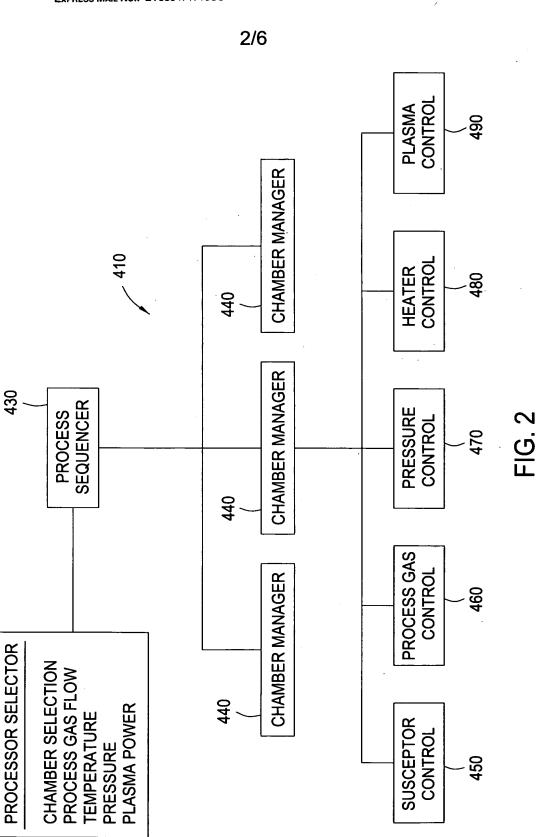
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ULTRA LOW DIELECTRIC MATERIALS BASED ON HYBRID SYSTEM OF LINEAR SILICON PRECURSOR
KANG SUB YM, ET AL.

INVENTOR:

PAGE 2 OF 6 EXPRESS MAIL No.: EV335471710US



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U.S. SERIAL NO.: UNKNOWN FILED: HEREWITH
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ULTRA LOW DIELECTRIC MATERIALS BASED ON HYBRID

SYSTEM OF LINEAR SILICON PRECURSOR KANG SUB YIM, ET AL.

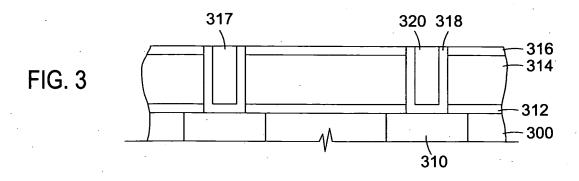
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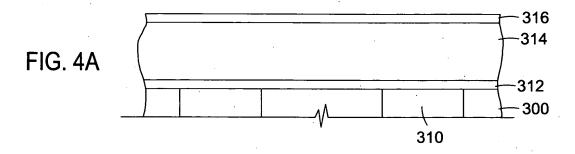
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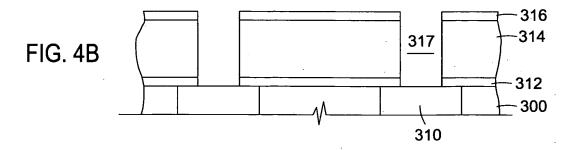
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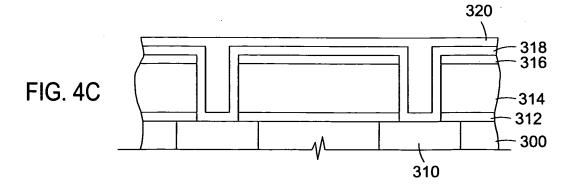
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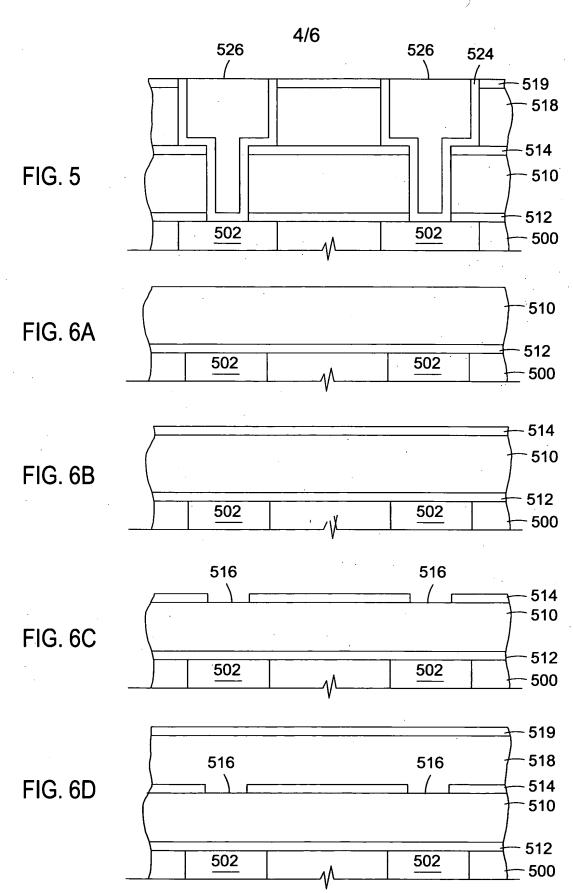
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ULTRA LOW DIELECTRIC MATERIALS BASED ON HYBRID SYSTEM OF LINEAR SILICON PRECURSOR TITLE:

INVENTOR: KANG SUB YIM, ET AL.
EXPRESS MAIL NO.: EV335471710US

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PAGE 4 OF 6



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APPLICANT: TITLE:

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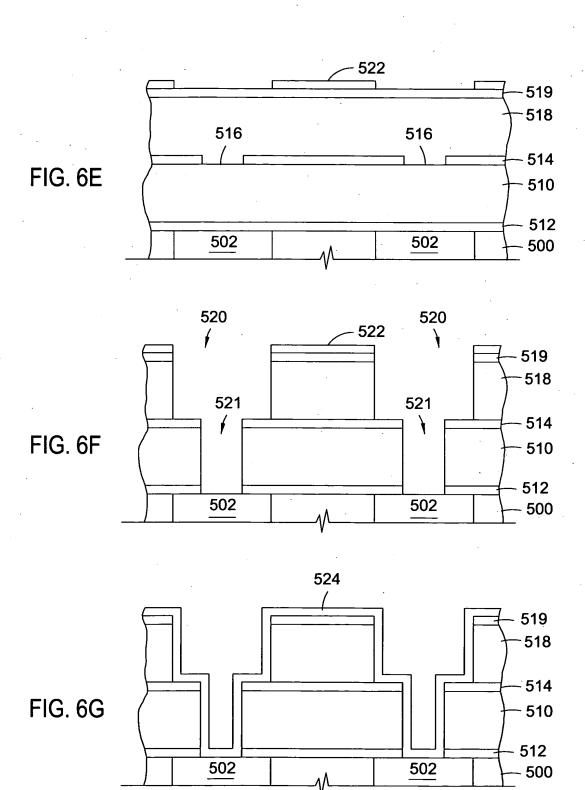
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ULTRA LOW DIELECTRIC MATERIALS BASED ON HYBRID
SYSTEM OF LINEAR SILICON PRECURSOR

KANG SUB YIM, ET AL. INVENTOR:

EXPRESS MAIL No.: EV335471710US

PAGE 5 OF 6

5/6



ATTY DKT. NO.: AMAT/7034.P1/DSM/LOW K/JW
U.S. SERIAL NO.: UNKNOWN FILED: HEREWITH
APPLICANT: APPLIED MATERIALS, INC.
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INVENTOR: KANG SUB YIM, ET AL.

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6/6

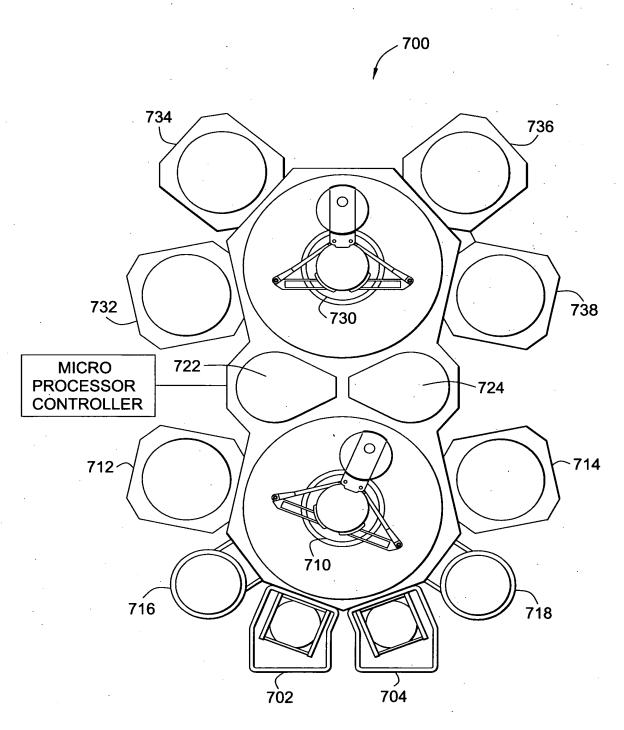


FIG. 7